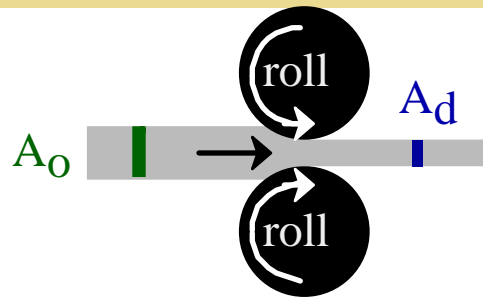
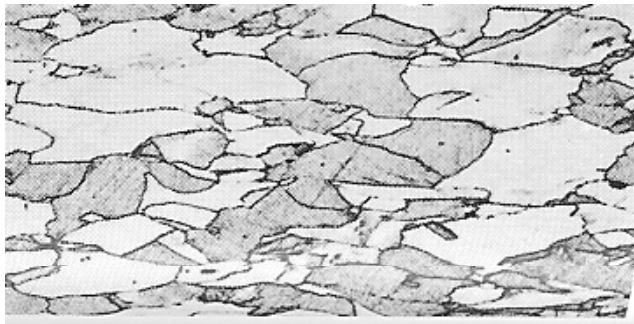


Cold Working

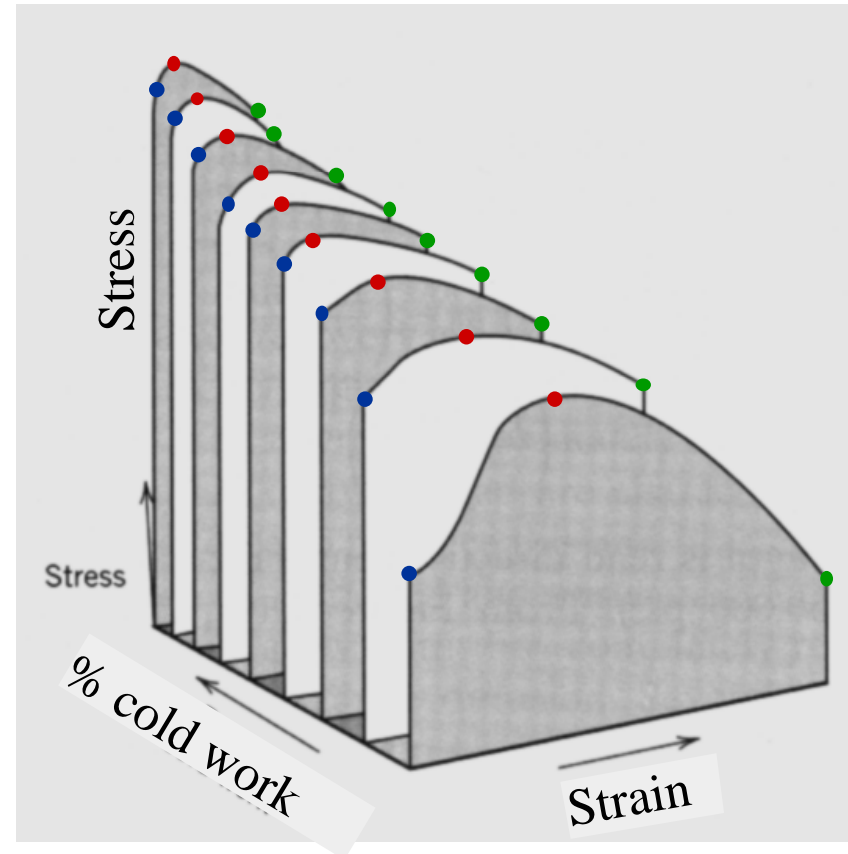


Rolling



Anisotropy

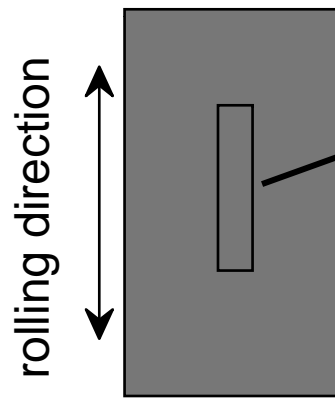
Traces of Slip bands



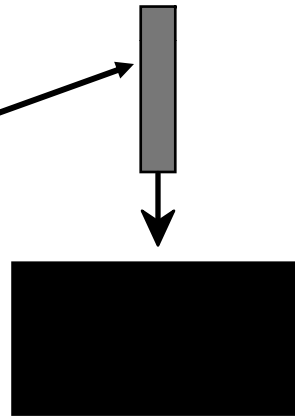
- Yield strength increases
- Tensile strength increases
- Strain Hardening decreases
- Uniform Elongation decreases
- Ductility decreases

ANISOTROPY IN DEFORMATION

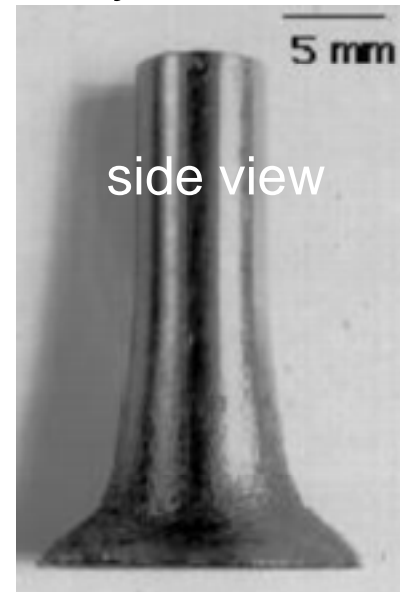
1. Cylinder of Tantalum machined from a rolled plate:



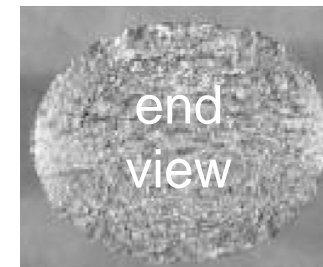
2. Fire cylinder at a target.



3. Deformed cylinder



Photos courtesy of G.T. Gray III, Los Alamos National Labs. Used with permission.

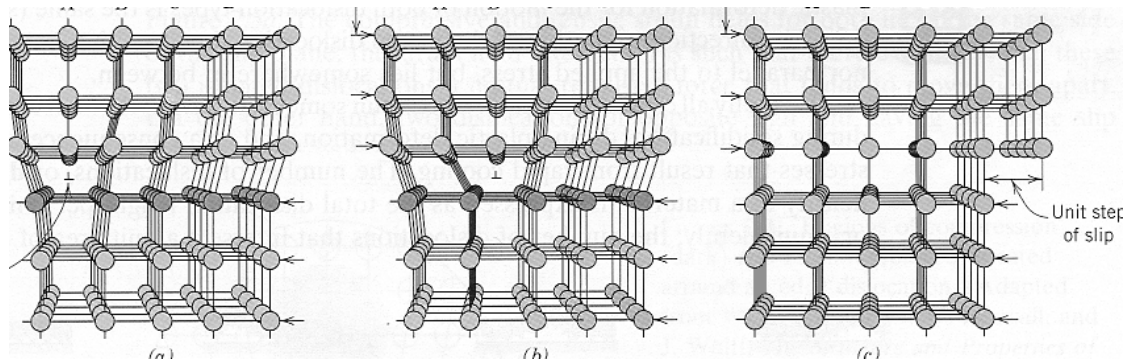


↑
plate thickness direction
↓

- The noncircular end view shows: anisotropic deformation of rolled material.

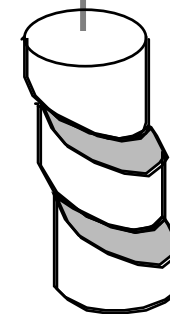
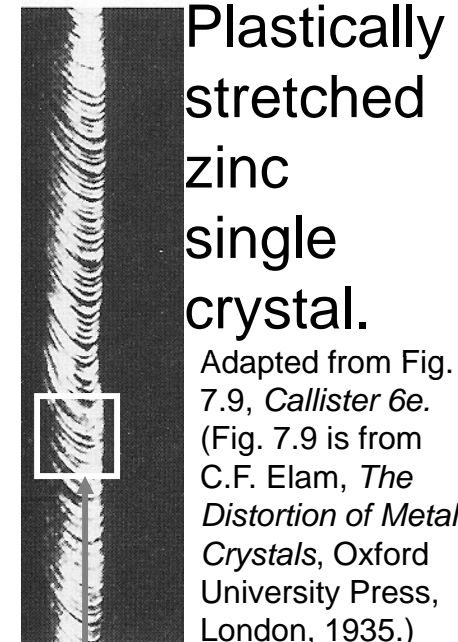
DISLOCATION MOTION

- Produces plastic deformation,
- Depends on incrementally breaking bonds.



Adapted from Fig. 7.1, *Callister 6e*. (Fig. 7.1 is adapted from A.G. Guy, *Essentials of Materials Science*, McGraw-Hill Book Company, New York, 1976. p. 153.)

- If dislocations don't move, deformation doesn't happen!



Adapted from Fig. 7.8, *Callister 6e*.

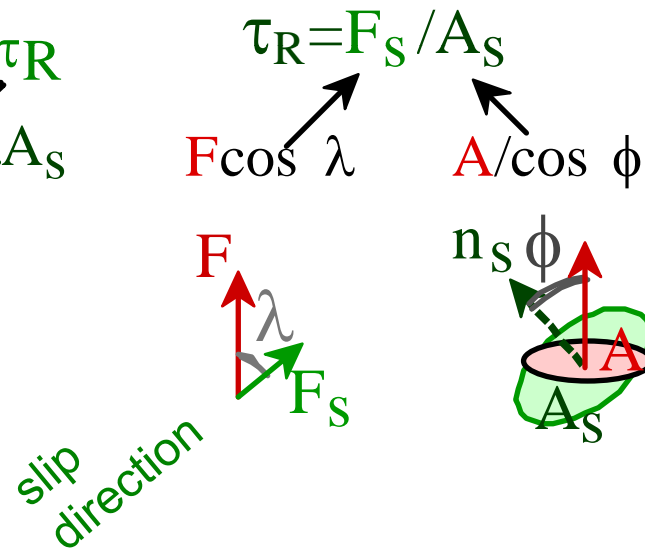
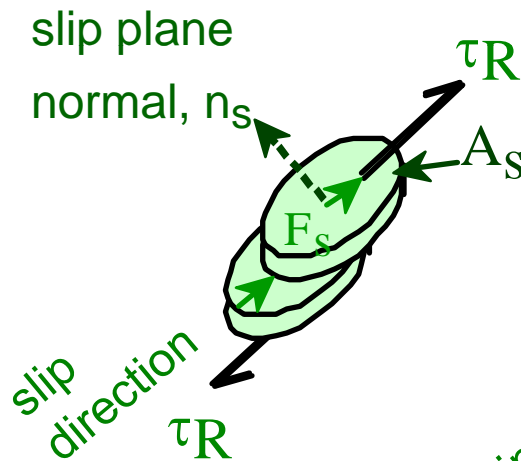
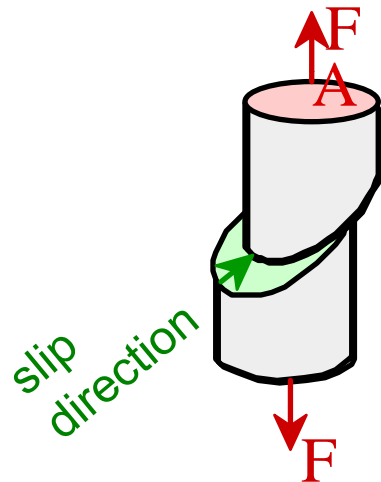
STRESS AND DISLOCATION MOTION

- Crystals slip due to a resolved shear stress, τ_R .
- Applied tension can produce such a stress.

Applied tensile stress: $\sigma = F/A$

Resolved shear stress: $\tau_R = F_S/A_S$

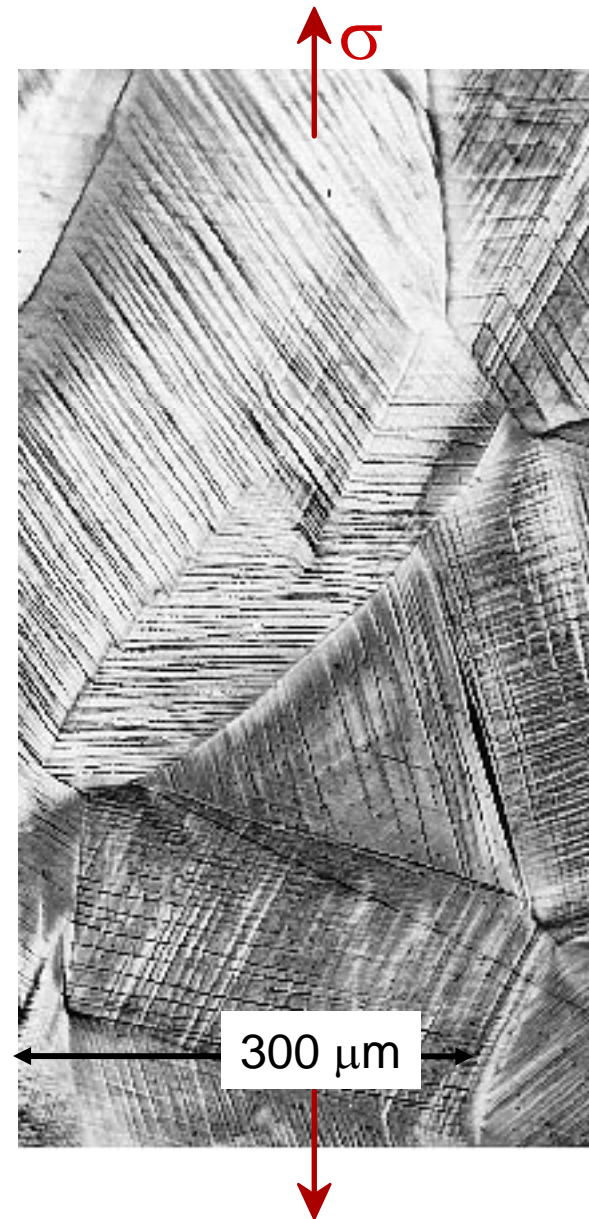
Relation between σ and τ_R



$$\tau_R = \sigma \cos \lambda \cos \phi$$

SLIP IN POLYCRYSTALS

- Slip planes & directions (λ , ϕ) change from one crystal to another.
- τ_R will vary from one crystal to another.
- The crystal with the largest τ_R yields first.
- Other (less favorably oriented) crystals yield later.



Adapted from Fig. 7.10, *Callister 6e*. (Fig. 7.10 is courtesy of C. Brady, National Bureau of Standards [now the National Institute of Standards and Technology, Gaithersburg, MD].)

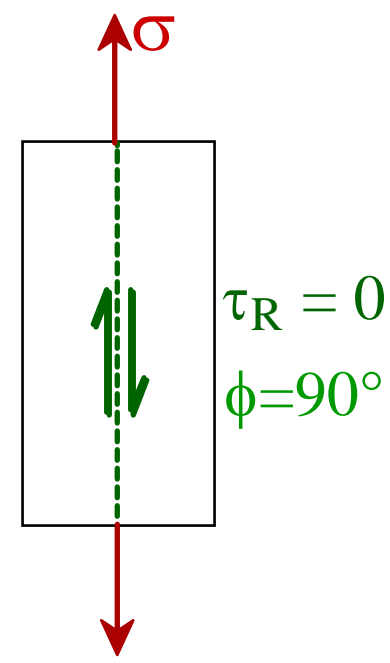
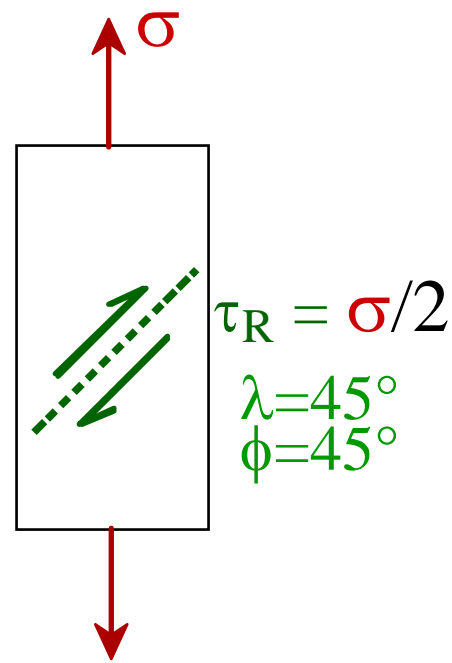
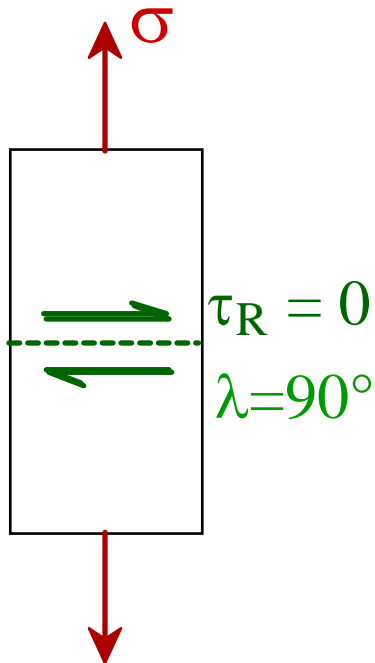
CRITICAL RESOLVED SHEAR STRESS

- Condition for dislocation motion:
- Crystal orientation can make it easy or hard to move disl.

$$\tau_R > \tau_{CRSS}$$

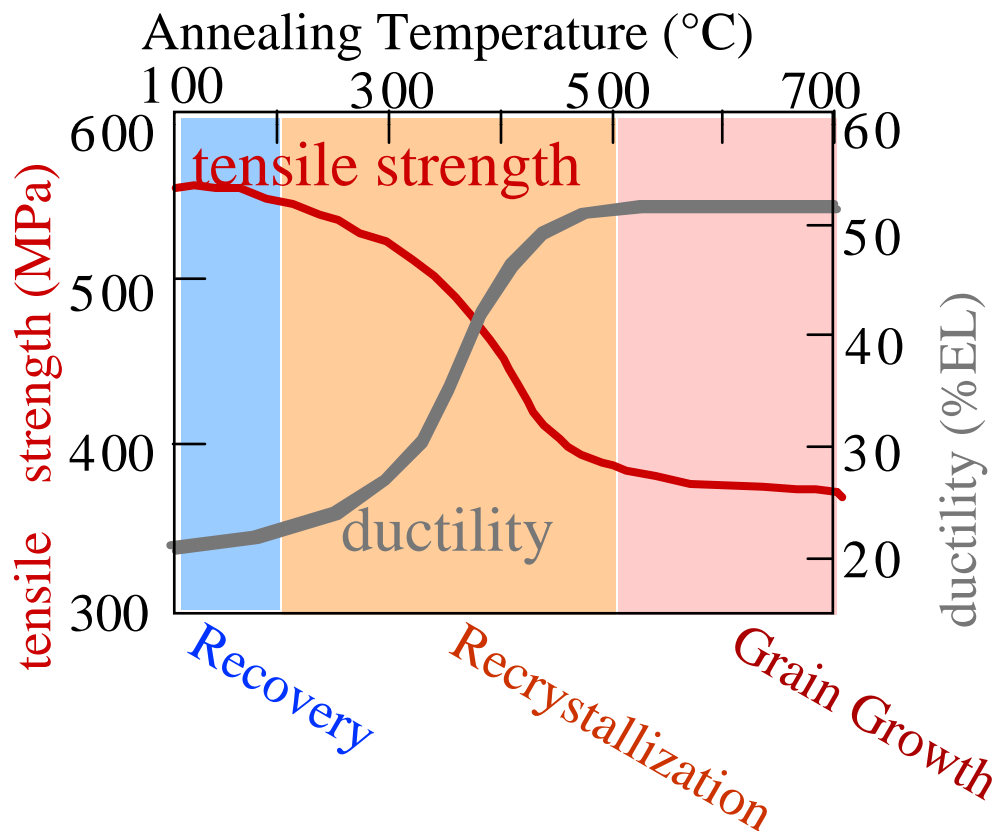
↑
typically
 $10^{-4}G$ to $10^{-2}G$

$$\tau_R = \sigma \cos \lambda \cos \phi$$



EFFECT OF HEATING AFTER %CW

- 1 hour treatment at T_{anneal} ...
decreases TS and increases %EL.
- Effects of cold work are reversed!

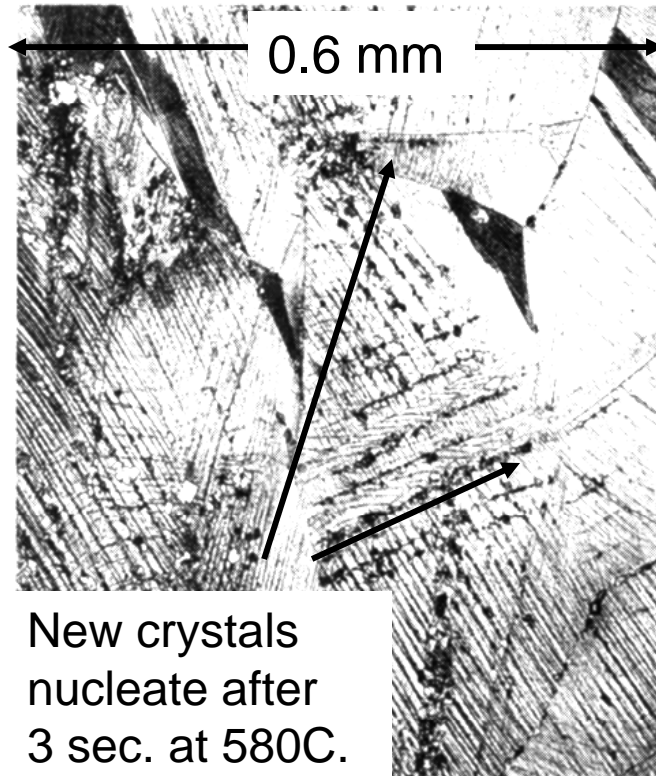
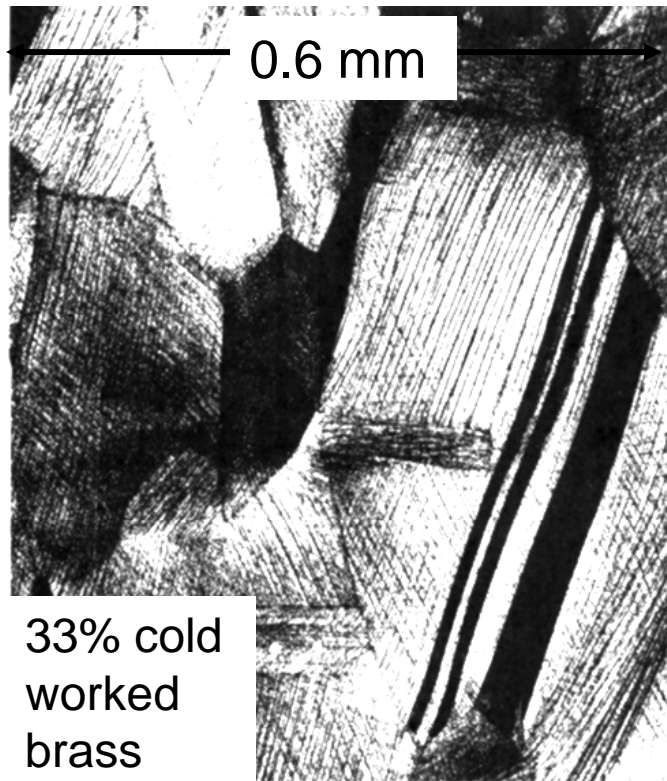


- **During recovery the dislocations move slightly and find lower energy arrangements. Atoms diffuse and reduce the number of vacancies to its equilibrium concentration.**
- **After recovery, physical properties such as electrical conductivity and corrosion resistance are recovered, but the strength is not!**

Adapted from Fig. 7.20, *Callister 6e*. (Fig. 7.20 is adapted from G. Sachs and K.R. van Horn, *Practical Metallurgy, Applied Metallurgy, and the Industrial Processing of Ferrous and Nonferrous Metals and Alloys*, American Society for Metals, 1940, p. 139.)

RECRYSTALLIZATION

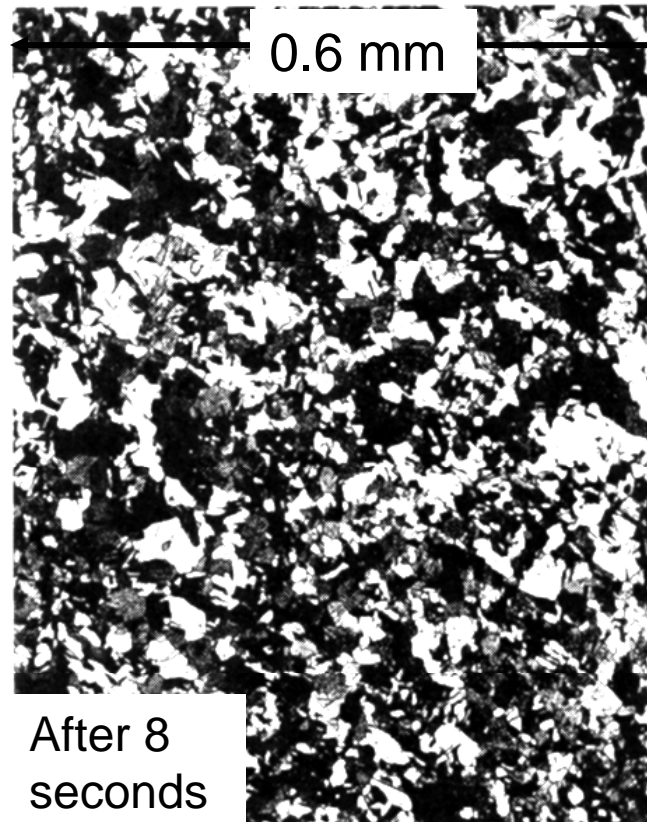
- New crystals are formed that:
 - have a small disl. density
 - are small
 - consume cold-worked crystals.



Adapted from Fig. 7.19 (a),(b), *Callister 6e*. (Fig. 7.19 (a),(b) are courtesy of J.E. Burke, General Electric Company.)

FURTHER RECRYSTALLIZATION

- All cold-worked crystals are consumed.

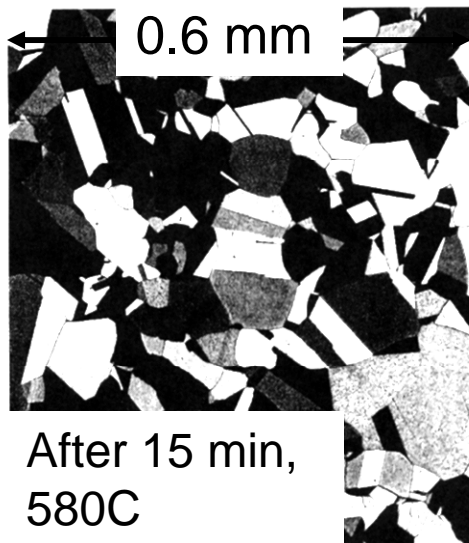
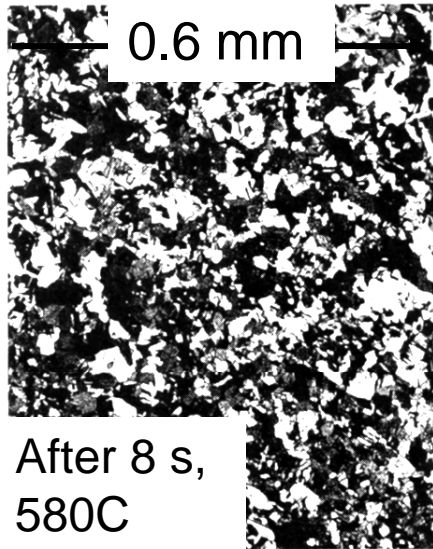


Adapted from
Fig. 7.19 (c),(d),
Callister 6e.
(Fig. 7.19 (c),(d)
are courtesy of
J.E. Burke,
General Electric
Company.)

$Y = 1 - \exp(-Kt^n)$, $Y =$ Fraction transformed
Avrami Equation

GRAIN GROWTH

- At longer times, larger grains consume smaller ones.
- Why? Grain boundary area (and therefore energy) is reduced.



Adapted from
Fig. 7.19 (d),(e),
Callister 6e.
(Fig. 7.19 (d),(e)
are courtesy of
J.E. Burke,
General Electric
Company.)

- Empirical Relation:

exponent typ. ~ 2
grain diam.
at time t.

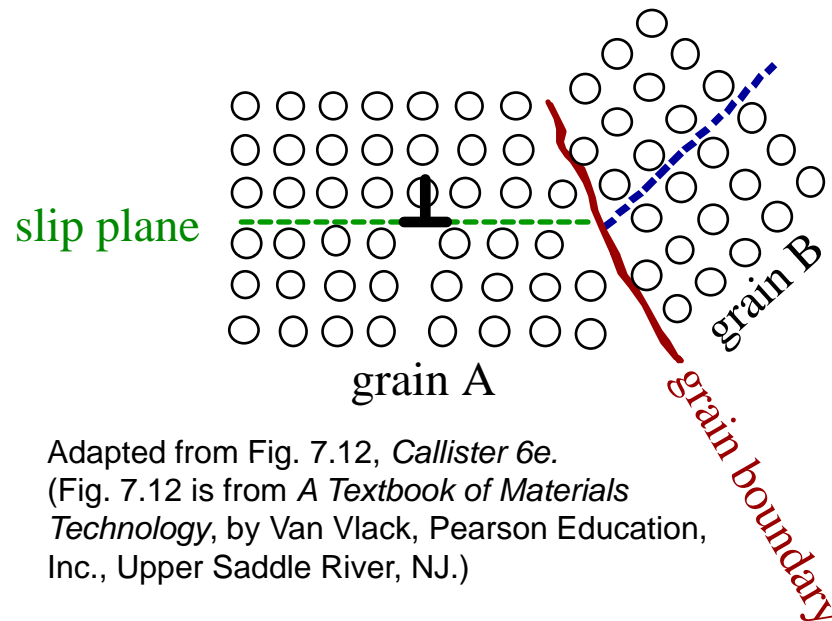
$$d^n - d_0^n = Kt$$

coefficient dependent
on material and T.

elapsed time

GRAIN BOUNDARY STRENGTHENING

- Grain boundaries are barriers to slip.
- Barrier "strength" increases with misorientation.
- Smaller grain size: more barriers to slip.



Adapted from Fig. 7.12, *Callister 6e*.
(Fig. 7.12 is from *A Textbook of Materials Technology*, by Van Vlack, Pearson Education, Inc., Upper Saddle River, NJ.)

- Hall-Petch Equation:

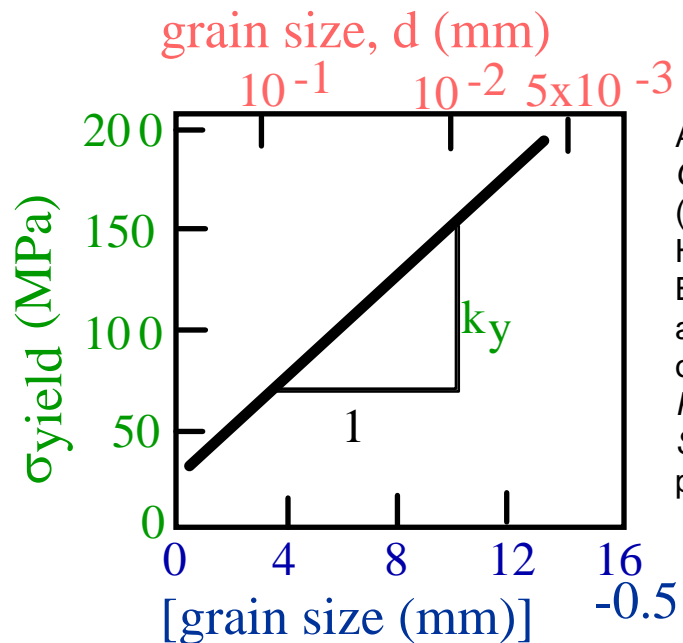
$$\sigma_{\text{yield}} = \sigma_0 + k_y d^{-1/2}$$

GRAIN SIZE STRENGTHENING: AN EXAMPLE

- 70wt%Cu-30wt%Zn brass alloy

$$\sigma_{\text{yield}} = \sigma_0 + k_y d^{-1/2}$$

- Data:



Adapted from Fig. 7.13, *Callister 6e*.
(Fig. 7.13 is adapted from H. Suzuki, "The Relation Between the Structure and Mechanical Properties of Metals", Vol. II, *National Physical Laboratory Symposium No. 15*, 1963, p. 524.)



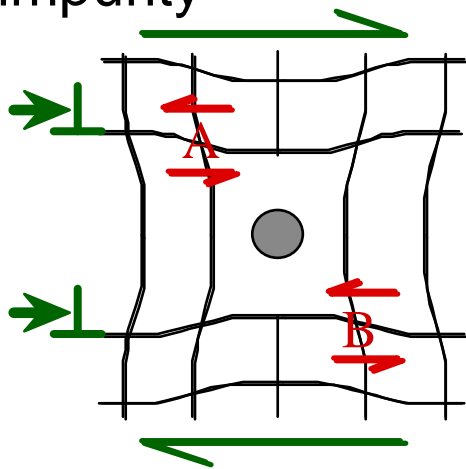
← 0.75mm →

Adapted from Fig. 4.11(c), *Callister 6e*. (Fig. 4.11(c) is courtesy of J.E. Burke, General Electric Co.)

SOLID SOLUTION STRENGTHENING

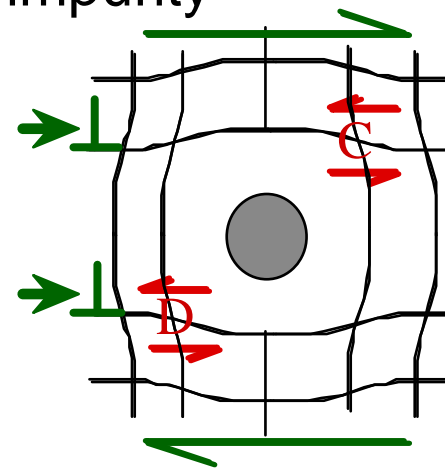
- Impurity atoms distort the lattice & generate stress.
- The stress field of the dislocations interact with the stress field of impurities, and therefore, higher stresses are needed to move the dislocations.

- Smaller substitutional impurity



Impurity generates local shear stress at A and B that opposes dislocation motion to the right.

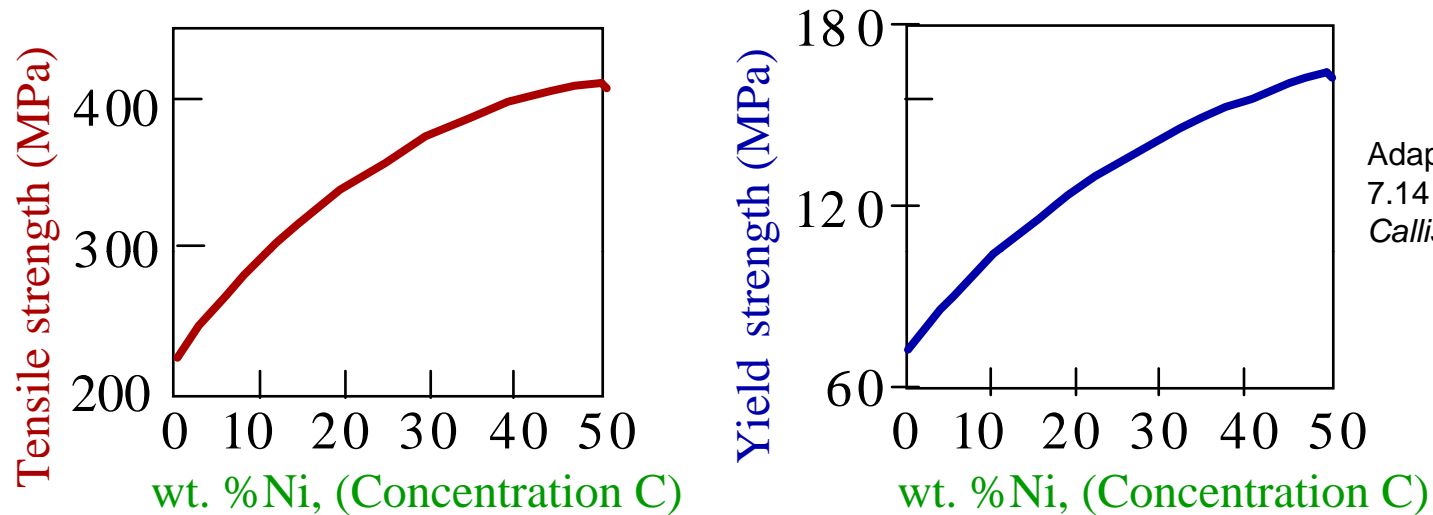
- Larger substitutional impurity



Impurity generates local shear stress at C and D that opposes dislocation motion to the right.

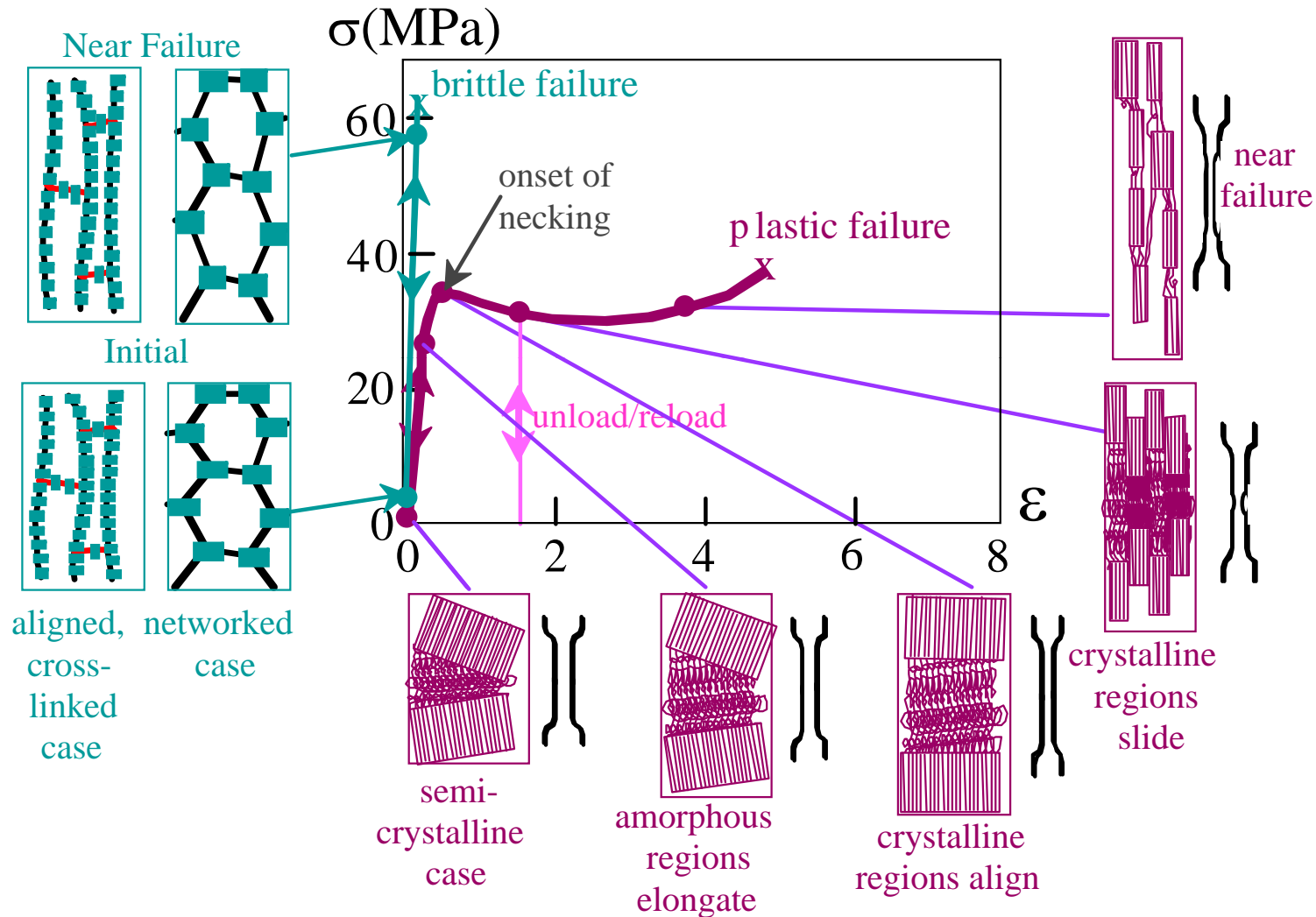
EXAMPLE: SOLID SOLUTION STRENGTHENING IN COPPER

- Tensile strength & yield strength increase with wt% Ni.



- Empirical relation: $\sigma_y \sim C^{1/2}$
- Alloying increases σ_y and TS.

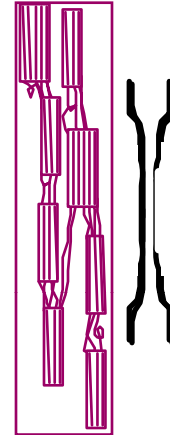
TENSILE RESPONSE: Polymers



Stress-strain curves adapted from Fig. 15.1, *Callister 6e*. Inset figures along plastic response curve (purple) adapted from Fig. 15.12, *Callister 6e*. (Fig. 15.12 is from J.M. Schultz, *Polymer Materials Science*, Prentice-Hall, Inc., 1974, pp. 500-501.)

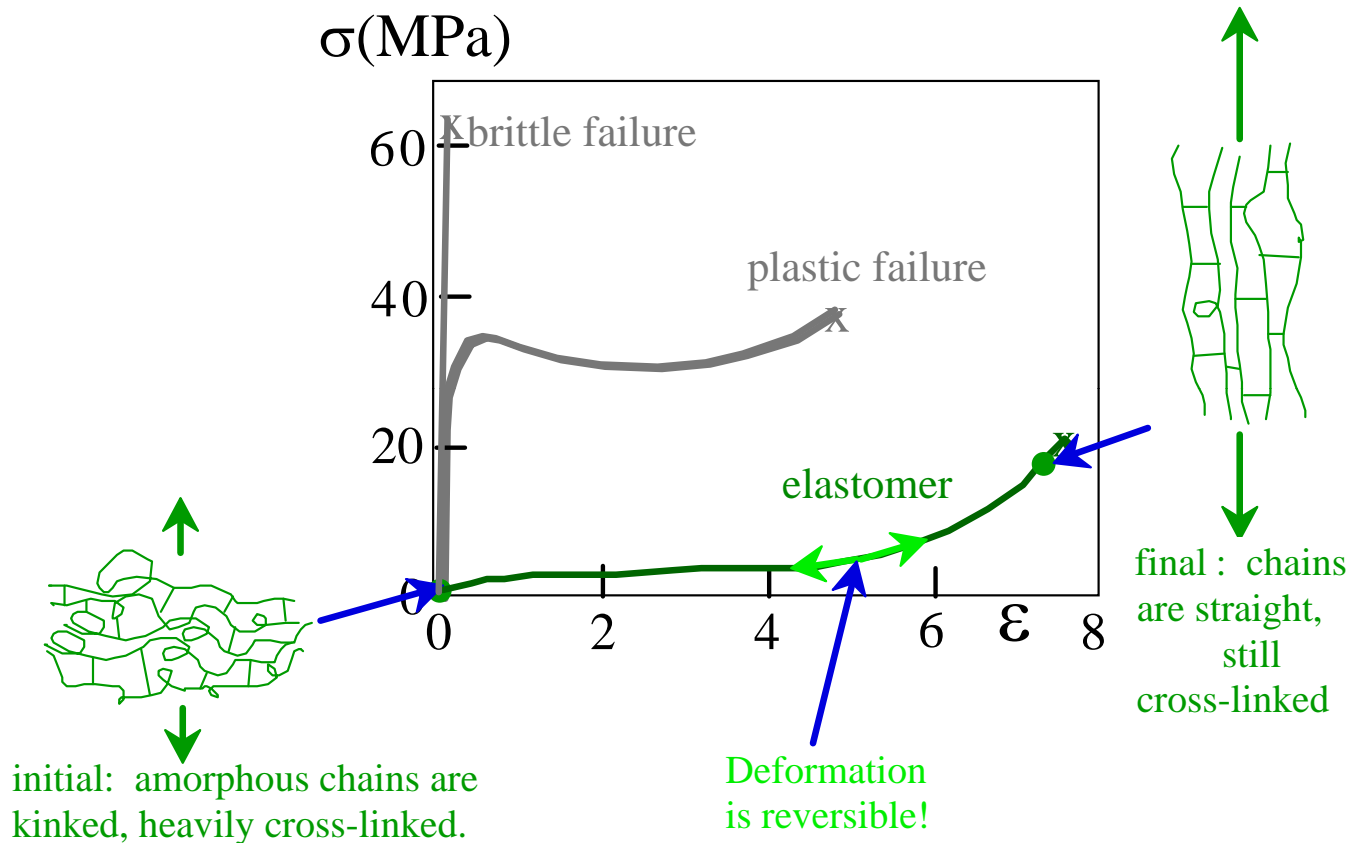
DEFORMATION BY DRAWING: Polymers

- **Drawing**...
 - stretches the polymer prior to use
 - aligns chains to the stretching direction
- Results of drawing:
 - increases the elastic modulus (E) in the stretching dir.
 - increases the tensile strength (TS) in the stretching dir.
 - decreases ductility (%EL)
- **Annealing** after drawing...
 - decreases alignment
 - reverses effects of drawing.
- Compare to **cold working** in metals!



Adapted from Fig. 15.12, *Callister 6e*. (Fig. 15.12 is from J.M. Schultz, *Polymer Materials Science*, Prentice-Hall, Inc., 1974, pp. 500-501.)

TENSILE RESPONSE: ELASTOMER CASE



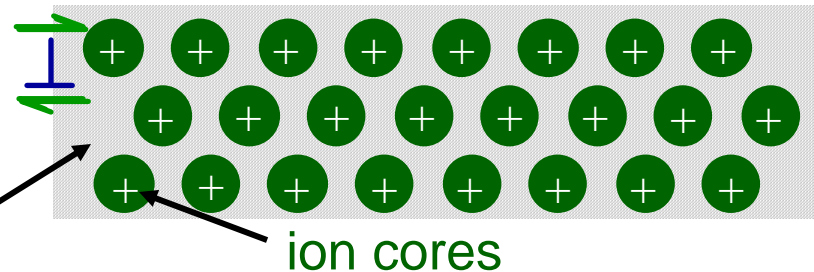
Stress-strain curves adapted from Fig. 15.1, *Callister 6e*. Inset figures along elastomer curve (green) adapted from Fig. 15.14, *Callister 6e*. (Fig. 15.14 is from Z.D. Jastrzebski, *The Nature and Properties of Engineering Materials*, 3rd ed., John Wiley and Sons, 1987.)

- Compare to responses of other polymers:
 - brittle response (aligned, cross linked & networked case)
 - plastic response (semi-crystalline case)

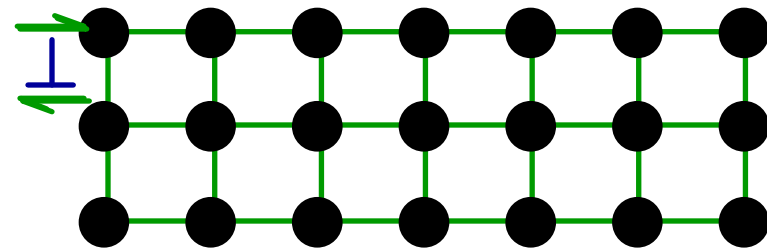
DISLOCATIONS & MATERIALS CLASSES

- Metals: Disl. motion easier.
 - non-directional bonding
 - close-packed directions for slip.

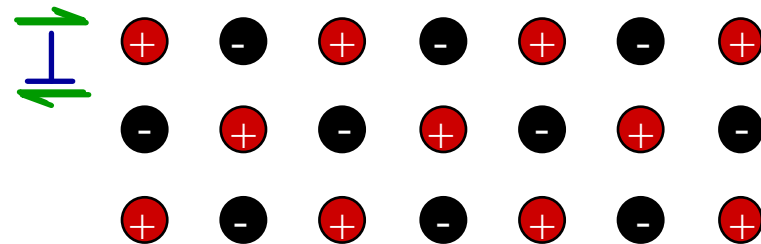
electron cloud



- Covalent Ceramics (Si, diamond): Motion hard.
 - directional (angular) bonding



- Ionic Ceramics (NaCl): Motion hard.
 - need to avoid ++ and -- neighbors.



Tensile Behavior of Ceramics

- Fracture precedes plastic deformation in ceramics, therefore they are brittle.
- Porosity plays an important role in mechanical properties!

